

### Description

#### Features

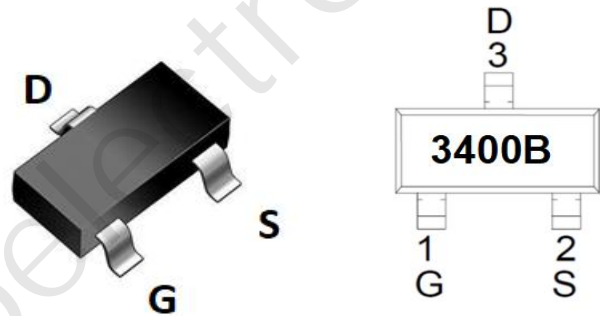
- 35V, 5.5A  
 $R_{DS(ON)}$  Typ = 24mΩ @  $V_{GS} = 10V$   
 $R_{DS(ON)}$  Typ = 26mΩ @  $V_{GS} = 4.5V$   
 $R_{DS(ON)}$  Typ = 36mΩ @  $V_{GS} = 2.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead Free



Schematic Diagram

#### Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

#### Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMLTU3400B	3400B	SOT-23	TAPING	7"	3000	120000

#### Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	35	V
$V_{GS}$	Gate-to-Source Voltage	±12	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ\text{C}$	5.5
		$T_A = 100^\circ\text{C}$	3.3
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	22	A
$P_D$	Power Dissipation	$T_A = 25^\circ\text{C}$	1.56
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(2)</sup>	80	°C/W
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	°C

### Electrical Characteristics ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
Off Characteristics							
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	35	-	-	V	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 35V, V <sub>GS</sub> = 0V	-	-	1.0	μA	
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±12V	-	-	±100	nA	
On Characteristics							
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.5	0.9	1.3	V	
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 2.5A	-	24	31	mΩ	
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 2A	-	26	34	mΩ	
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 1.5A	-	36	47	mΩ	
Dynamic Characteristics							
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 15V, f = 1MHz	-	739	-	pF	
C <sub>oss</sub>	Output Capacitance		-	47	-	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	39	-	pF	
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 10V V <sub>DS</sub> = 15V, I <sub>D</sub> = 3A	-	16	-	nC	
Q <sub>gs</sub>	Gate Source Charge		-	1.8	-	nC	
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	1.6	-	nC	
Switching Characteristics							
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 15V I <sub>D</sub> = 3A, R <sub>GEN</sub> = 3Ω	-	6	-	ns	
t <sub>r</sub>	Turn-On Rise Time		-	15	-	ns	
t <sub>d(off)</sub>	Turn-Off DelayTime		-	30	-	ns	
t <sub>f</sub>	Turn-Off Fall Time		-	3.5	-	ns	
Drain-Source Diode Characteristics and Max Ratings							
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current	V <sub>GS</sub> = 0V, I <sub>S</sub> = 2A	-	-	5.5	A	
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	22	A	
V <sub>SD</sub>	Drain to Source Diode Forward Voltage		-	-	1.2	V	
trr	Body Diode Reverse Recovery Time		-	9	-	ns	
Qrr	Body Diode Reverse Recovery Charge		I <sub>F</sub> = 3A, di/dt = 100A/us	-	3.6	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2.  $R_{\theta JA}$  is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB
  3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

## Test Circuit

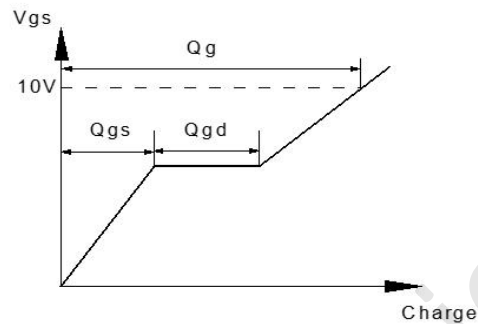


Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform

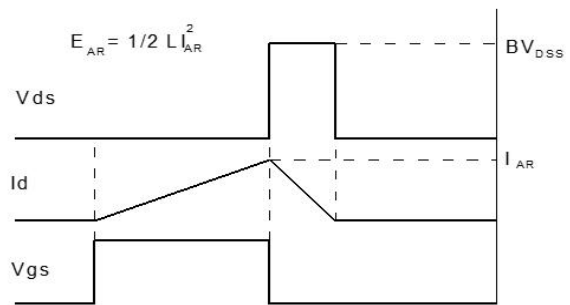


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

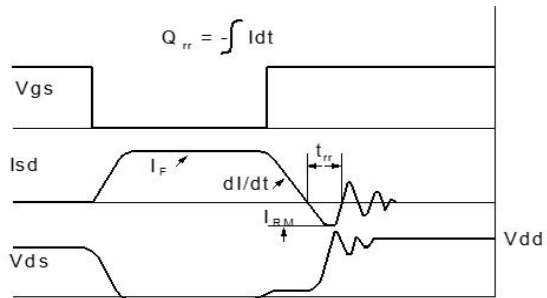
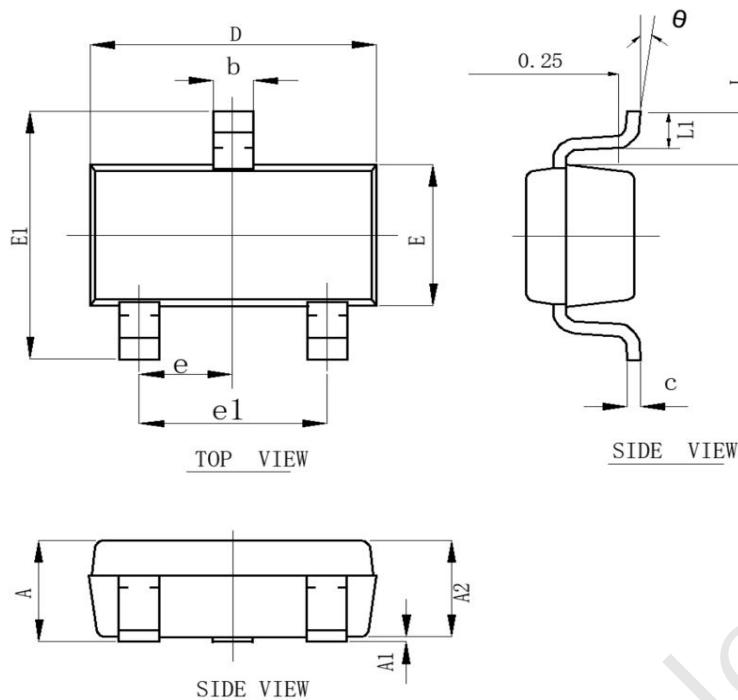


Figure 4: Diode Recovery Test Circuit & Waveform

### Package Mechanical Data(SOT-23)




COMMON DIMENSIONS In Millimeters		
SYMBOL	MIN	MAX
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
L	0.550	REF.
θ	0°	8°
L1	0.300	0.500
e	0.950	TYP.
e1	1.800	2.000

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